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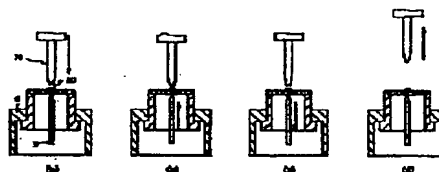
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(54) DIE-BONDING DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To facilitate the setting operation of a lift-up pin before die-bonding in a die-bonding device.

SOLUTION: A contact sensor, which detects the state wherein a tool 18 comes in contact with a chip 50, is provided. After the tool 18 has been brought down to an attracting position (a), the chip 50 is lifted up by raising the contact sensor (b). The movement of the lift-up pin 9 is controlled from the moving position of the lift-up pin 9 at the point of time when the chip 50 comes in contact with the tool 18 is detected by the contact sensor. Accordingly, the setting operation of the reference movement position of the lift-up pin 9 and the movement position of the lift-up pin 9 when an attraction operation is conducted, are unnecessitated.



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